

**Listing of the Claims**

1. - 14. (Cancelled)

15. (Original) An IC chip having substantially flattened solder bumps on an active surface comprising:

a multiplicity of bond pads formed on said active surface, and

a multiplicity of solder bumps formed in flattened hemi-spherical shape on said multiplicity of bond pads, each of said multiplicity of solder bumps having a height less than  $\frac{1}{2}$  of the maximum diameter of said hemi-spherical shapes.

16. (Original) An IC chip having substantially flattened solder bumps on an active surface according to claim 15, wherein said multiplicity of solder bumps is formed of a lead-containing solder material.

17. (Original) An IC chip having substantially flattened solder bumps on an active surface according to claim 15, wherein said multiplicity of solder bumps is formed of a soft solder material and flattened on the top surfaces by a flat platen.

18. (Original) An IC chip having flat solder bumps on an active surface comprising:

a multiplicity of bond pads formed on said active surface, and  
a multiplicity of solder bumps formed in cylindrical shape on said multiplicity of bond pads, each of said multiplicity of solder bumps having a height less than  $\frac{1}{2}$  of the diameter of said cylindrical shape.

19. (Original) An IC chip having flat solder bumps on an active surface according to claim 18, wherein said multiplicity of solder bumps is formed of a lead-containing solder material.

20. (Original) An IC chip having flat solder bumps on an active surface according to claim 18, wherein said multiplicity of solder bumps is formed in a pancake shape.